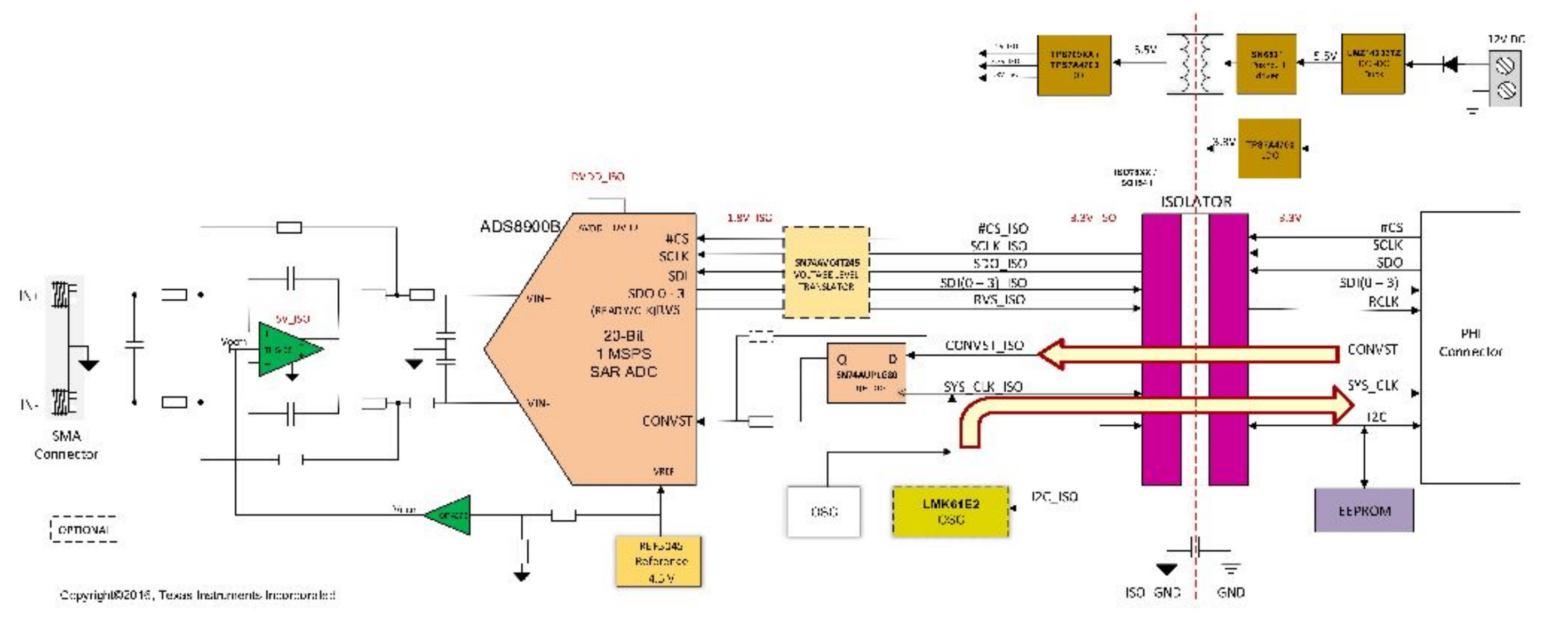


Revision History				
Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



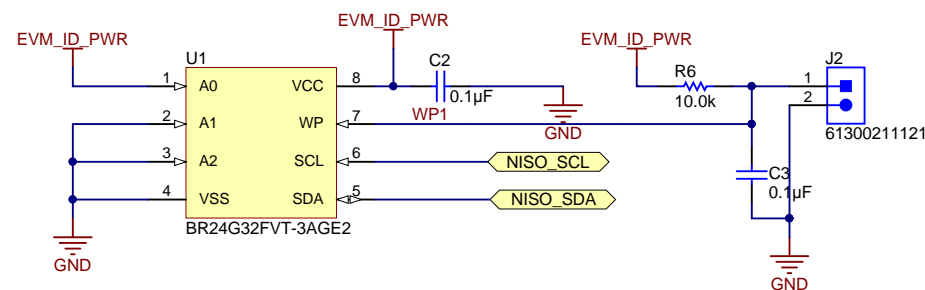
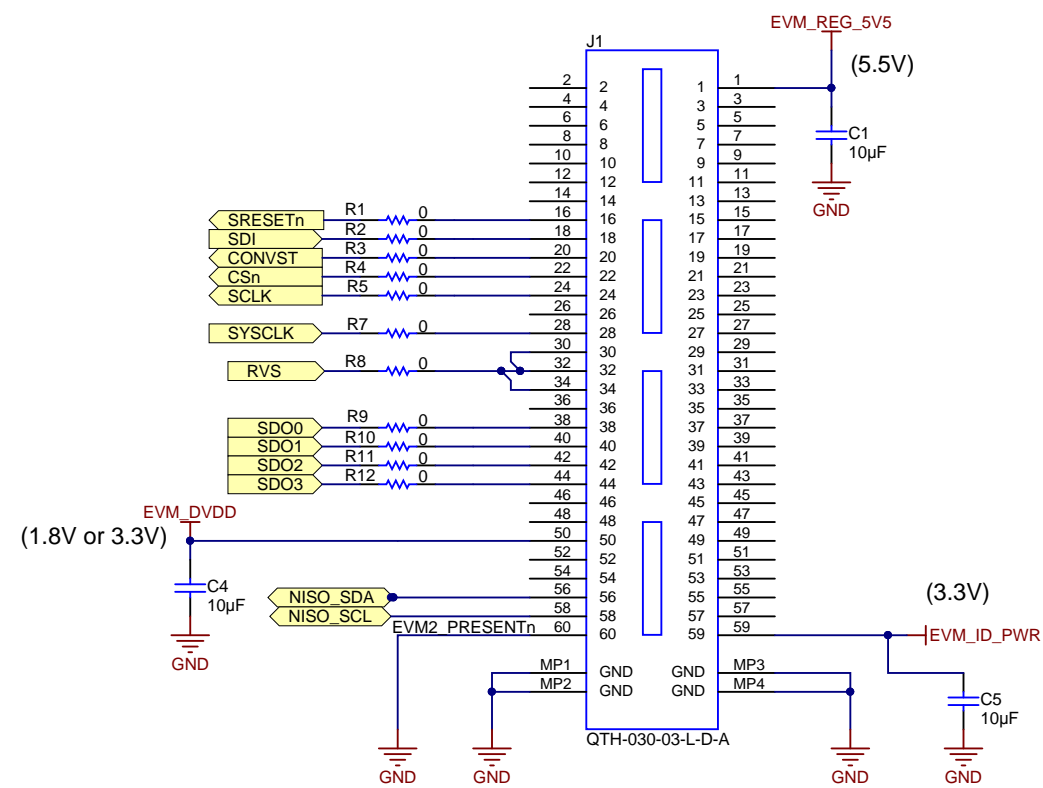
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TID #: 01035	Project Title: 20-bit, 1-MSPS Isolator Optimized Data Acquisition	
Number: TIDA-01035	Rev: E1	Sheet: 1 of 6
SVN Rev: Not in version control	Assembly Variant: ADS8900B	Size: B
Drawn By:	File: TIDA-01035_CoverSheet_SchDoc	
Engineer: ANBU MANI	Contact: http://www.ti.com/support	

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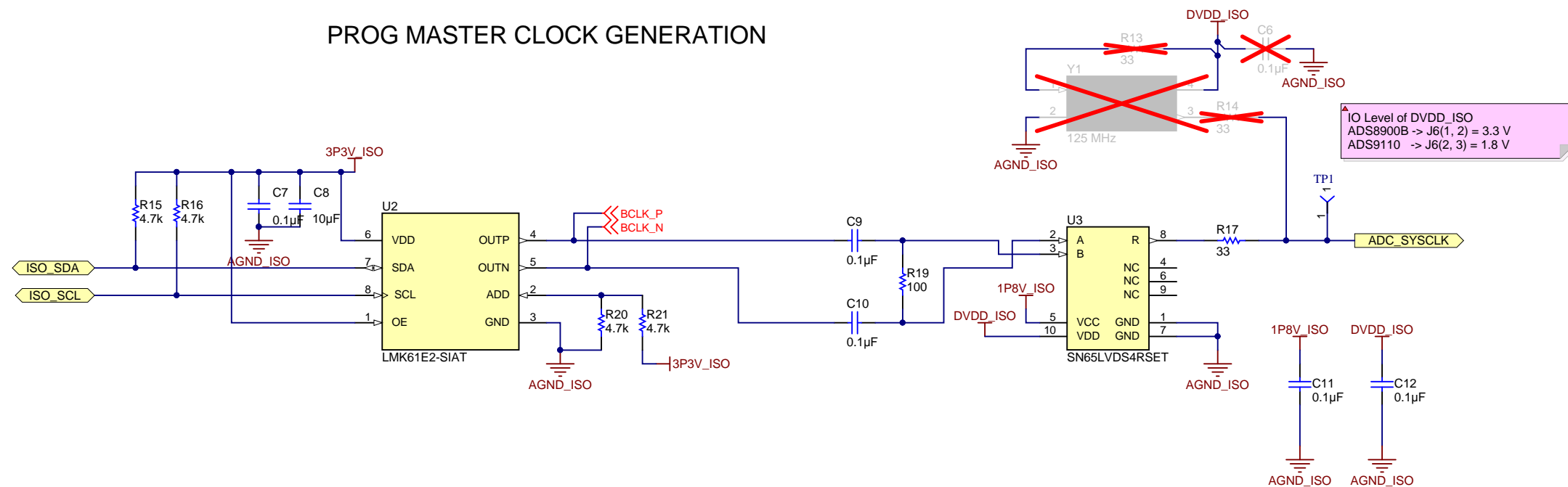
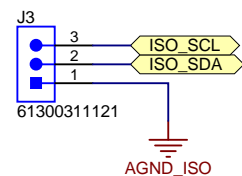


PHI PLATFORM INTERFACE WITH ISOLATION



PROG MASTER CLOCK GENERATION

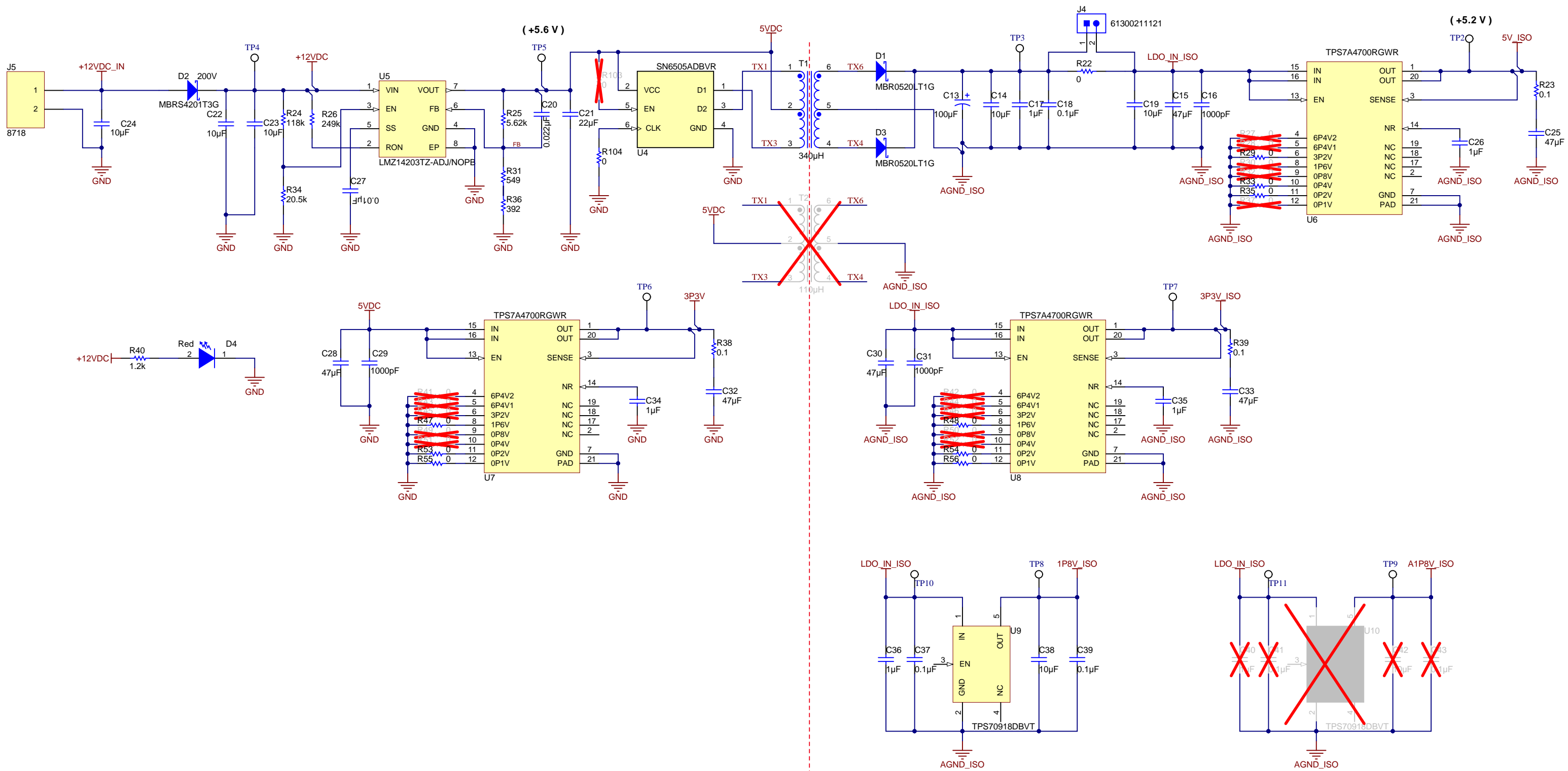
USB2ANY I2C HEADER



IO Level of DVDD_ISO
 ADS8900B -> J6(1, 2) = 3.3 V
 ADS9110 -> J6(2, 3) = 1.8 V

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Number: TIDA-01035	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: ADS8900B	Sheet: 2 of 6
Drawn By:	File: TIDA-01035_CONNECTOR.SchDoc	Size: B
Engineer: ANBU MANI	Contact: http://www.ti.com/support	



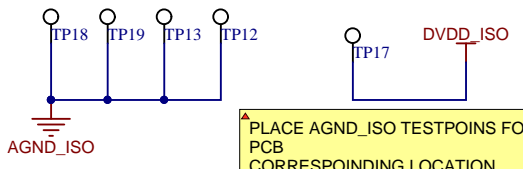
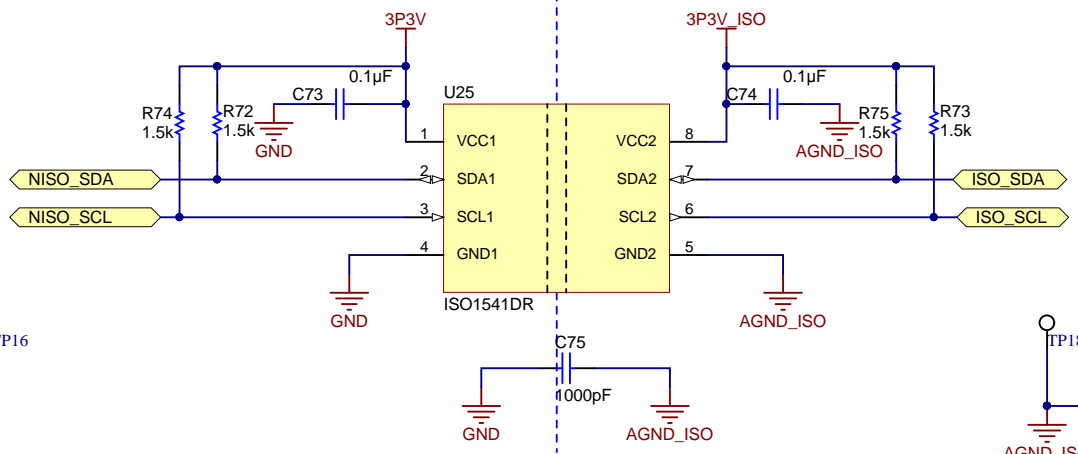
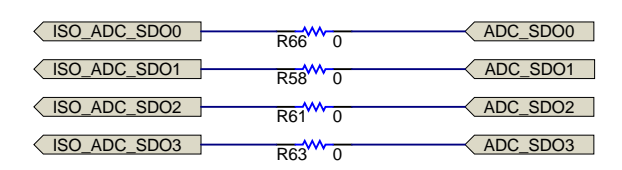
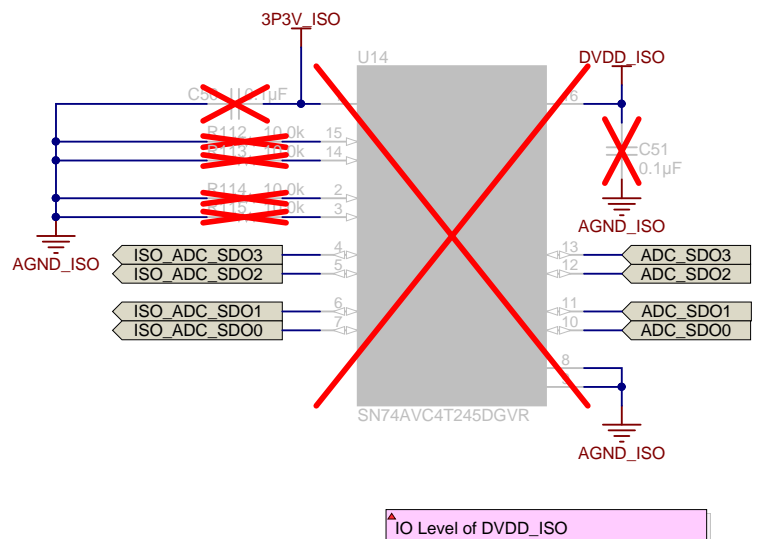
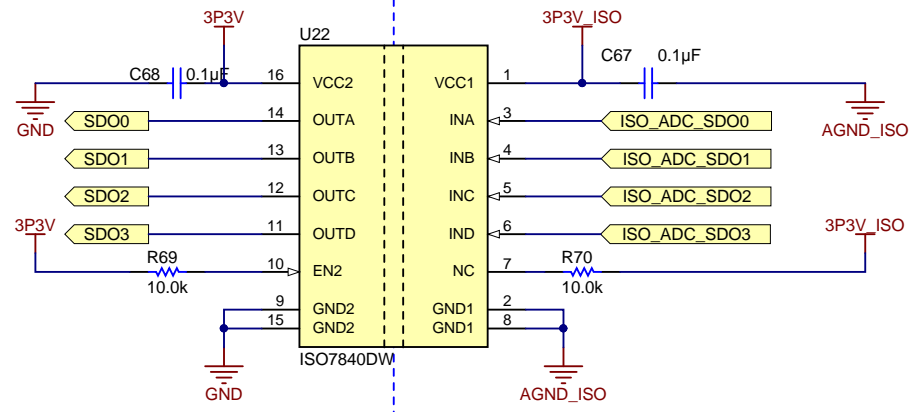
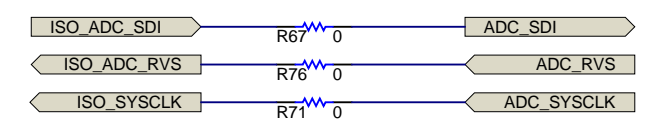
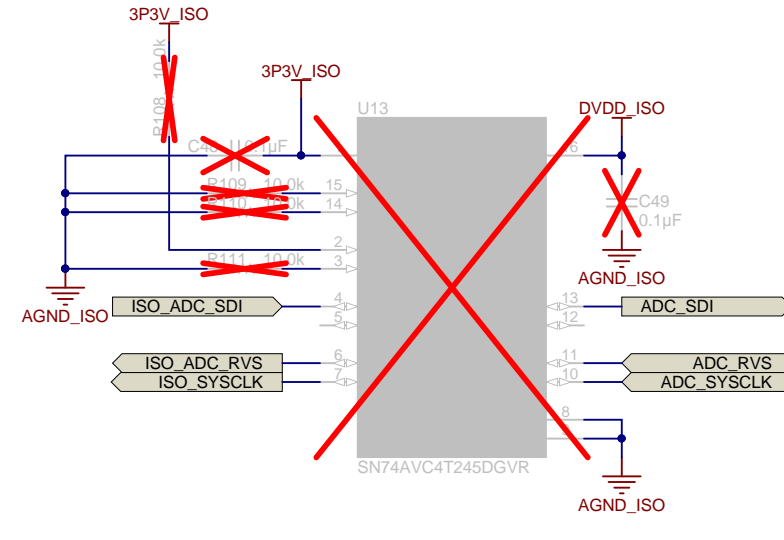
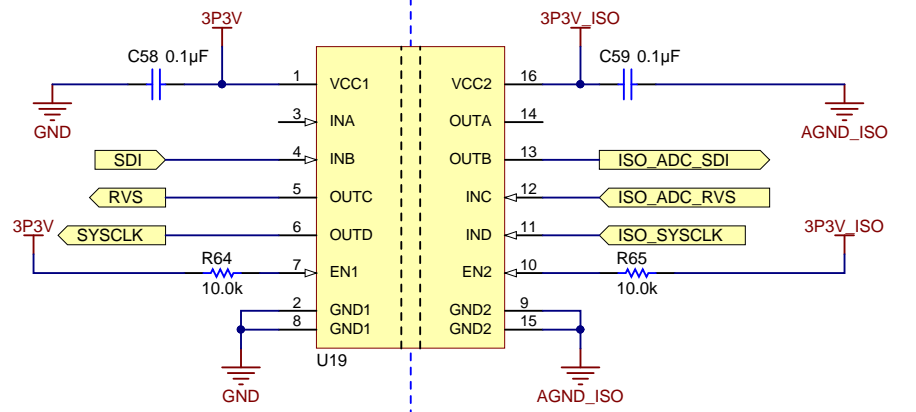
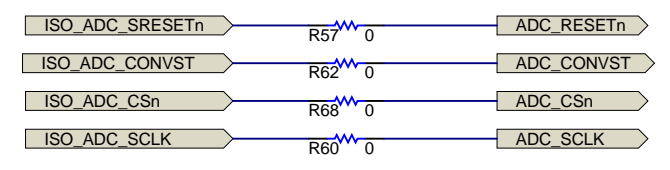
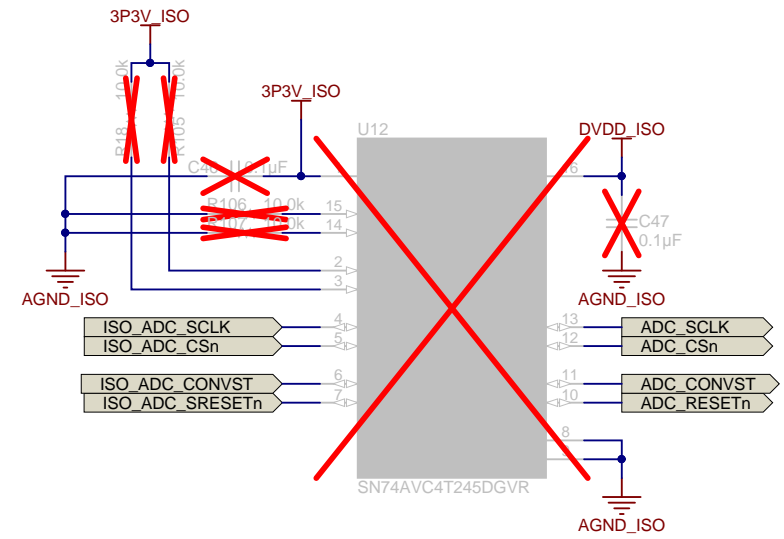
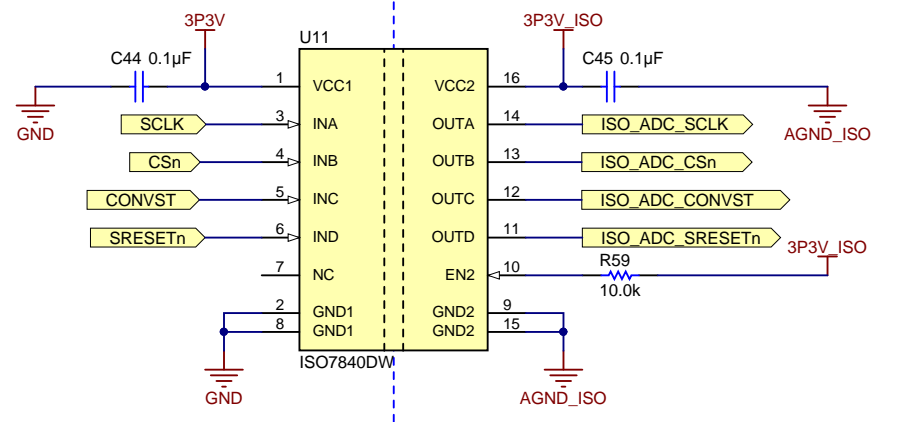
NON-ISOLATED POWER RAIL

ISOLATED POWER RAIL

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TID #: 01035	Project Title: 20-bit, 1-MSPS Isolator Optimized Data Acquisition	
Number: TIDA-01035	Rev: E1	Sheet Title: LDO's Isolated & Non Isolated
SVN Rev: Not in version control	Assembly Variant: ADS8900B	Sheet: 3 of 6
Drawn By: Anbu Mani	File: TIDA-01035_POWER_ISOLATION.SchDoc	Size: B
Engineer: ANBU MANI	Contact: http://www.ti.com/support	© Texas Instruments 2015





IO Level of DVDD_ISO
 ADS8900B -> J6(1, 2) = 3.3 V
 ADS9110 -> J6(2, 3) = 1.8 V

PLACE GND TESTPOINTS FOUR CORNER OF PCB CORRESPONDING LOCATION

PLACE AGND_ISO TESTPOINTS FOUR CORNER OF PCB CORRESPONDING LOCATION

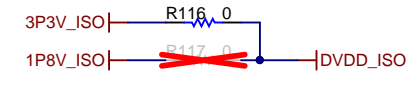
ISOLATION

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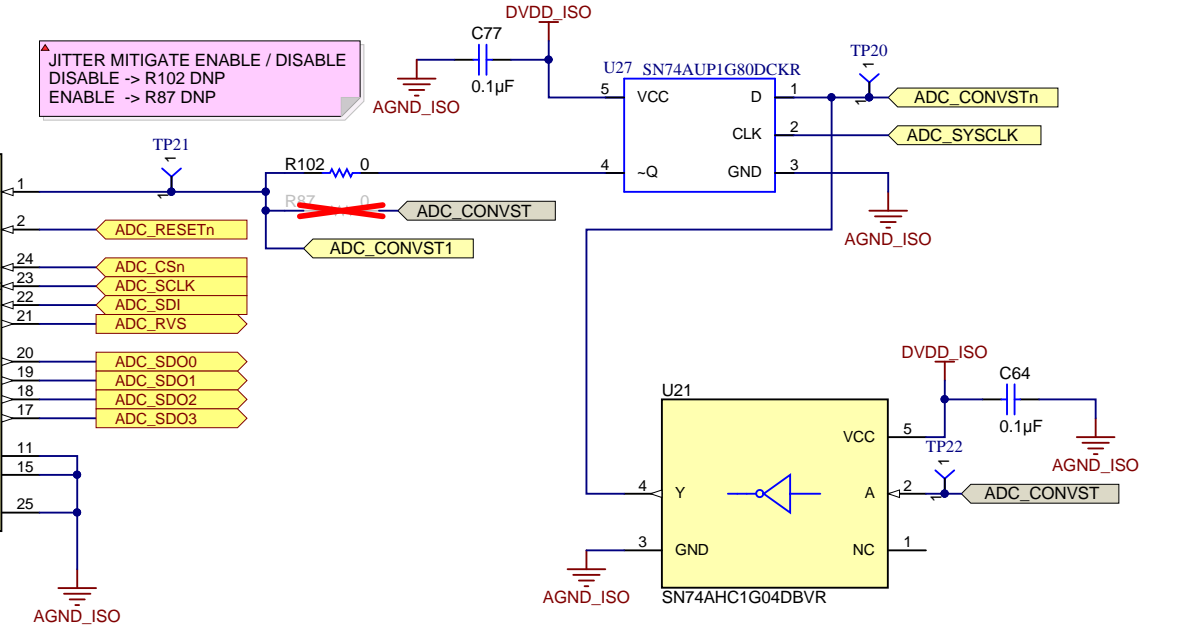
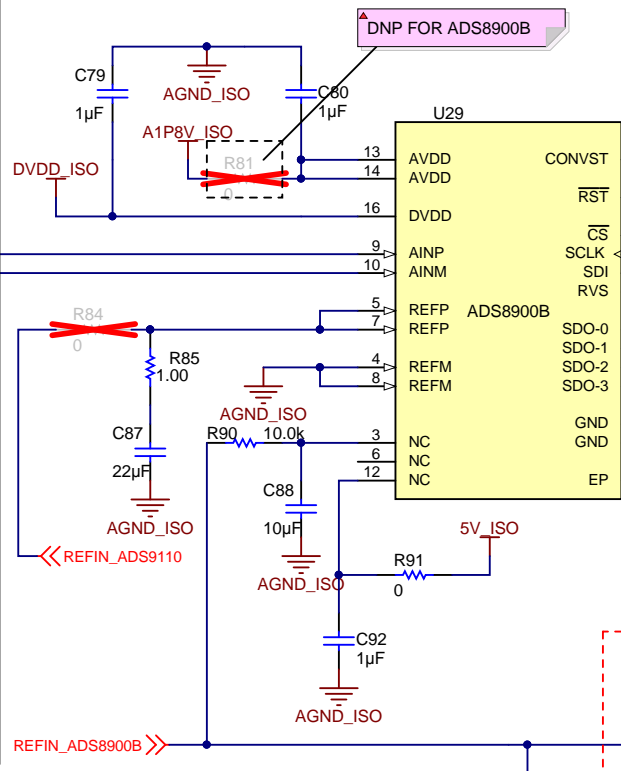
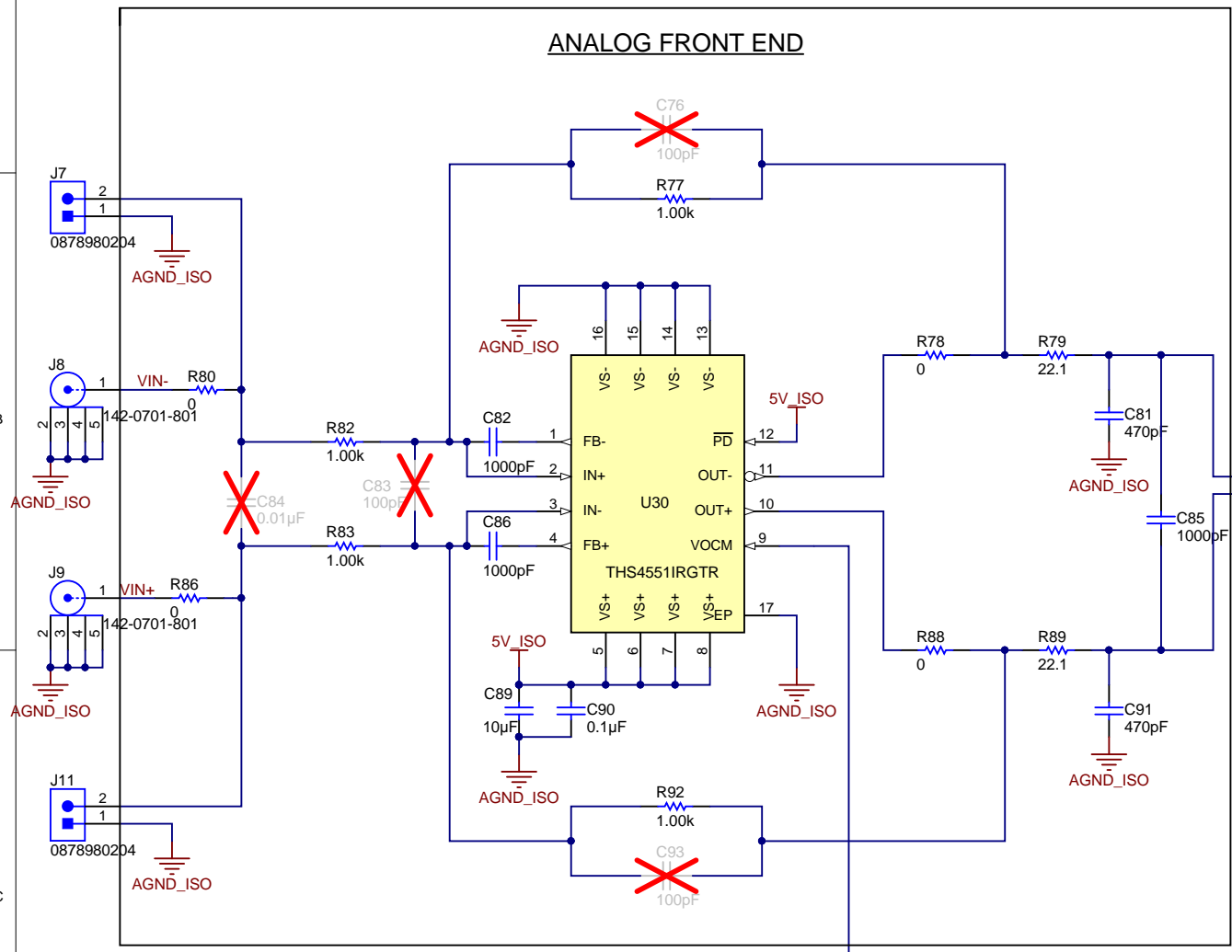
Orderable: N/A	Designed for: Public Release	Mod. Date: 12/2/2016
TID #: 01035	Project Title: 20-bit, 1-MSPS Isolator Optimized Data Acquisition	
Number: TIDA-01035	Rev: E1	Sheet Title:
SVN Rev: Not in version control	Assembly Variant: ADS8900B	Sheet: 4 of 6
Drawn By:	File: TIDA-01035_DATA_ISOLATION.SchDoc	Size: B
Engineer: ANBU MANI	Contact: http://www.ti.com/support	



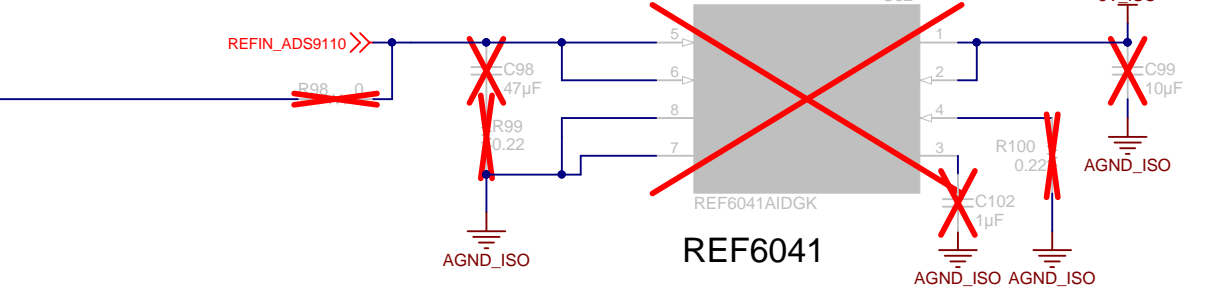
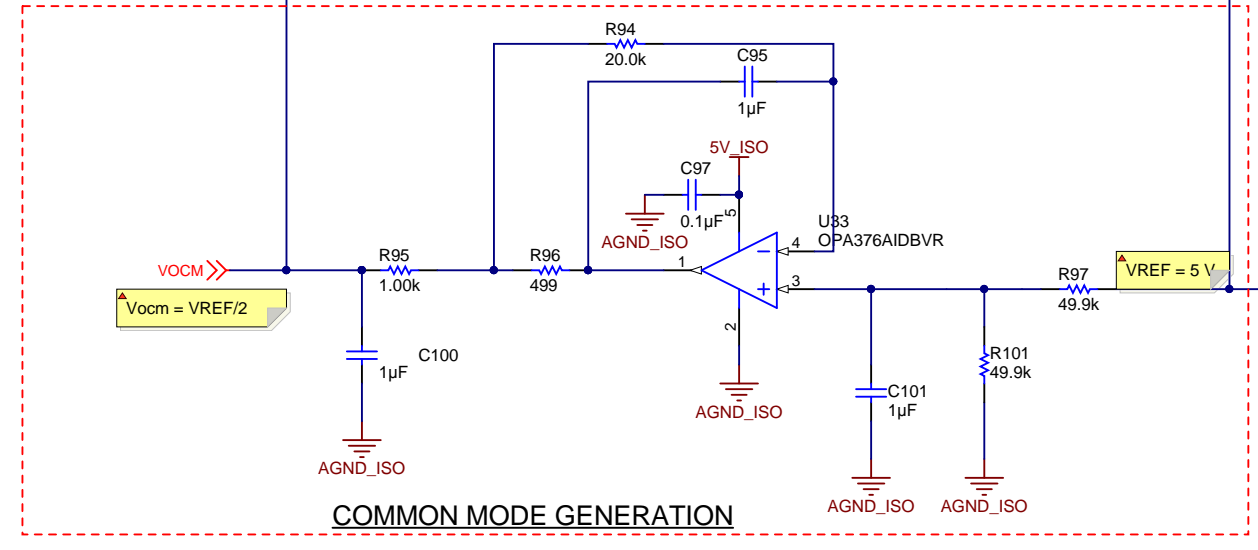
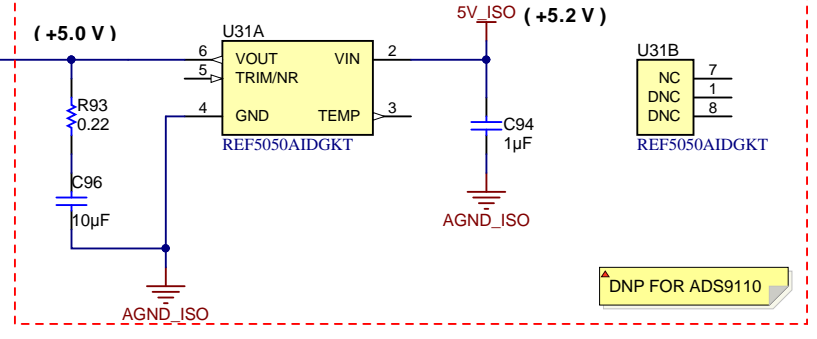
IO Level of DVDD_ISO
 ADS8900B -> R? / R? = 3.3 V
 ADS9110 -> R? / R? = 1.8 V



ANALOG FRONT END

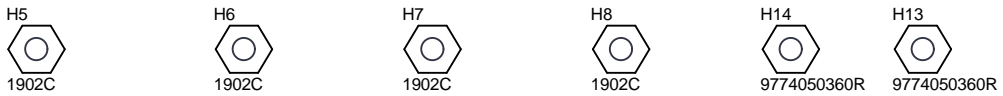
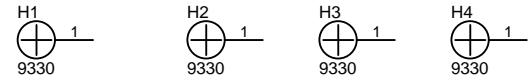


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TID #: 01035	Project Title: 20-bit, 1-MSPS Isolator Optimized Data Acquisition	Sheet: 5 of 6	
Number: TIDA-01035	Rev: E1	Size: B	
SVN Rev: Not in version control	Assembly Variant: ADS8900B	Sheet: 5 of 6	
Drawn By:	File: TIDA-01035_ADC1.SchDoc	Size: B	
Engineer: ANBU MANI	Contact: http://www.ti.com/support	Size: B	



PCB Number: TIDA-01035
PCB Rev: E1

PCB LOGO
Logo1

PCB LOGO
Pb-Free Symbol

PCB LOGO
Logo3

^ You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.


Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: 01035	Project Title: 20-bit, 1-MSPS Isolator Optimized Data Acquisition		
Number: TIDA-01035	Rev: E1	Sheet Title:	
SVN Rev: Not in version control	Assembly Variant: ADS8900B	Sheet: 6 of 6	
Drawn By: ANBU MANI	File: TIDA-01035_Hardware.SchDoc	Size: B	
Engineer: ANBU MANI	Contact: http://www.ti.com/support		

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